

Title (en)

LED module with cooling bodies containing mounting elements

Title (de)

LED-Modul mit Montagemittel umfassenden Kühlkörpern

Title (fr)

Module à DEL doté de corps de refroidissement comprenant un moyen de montage

Publication

**EP 2096685 A1 20090902 (DE)**

Application

**EP 08102125 A 20080228**

Priority

EP 08102125 A 20080228

Abstract (en)

The LED-module (1) has LED-components (3) mounted on a printed circuit board (2) such that the LED-components are directly or indirectly connected with a heat sink (4) through an opening of the circuit board. The heat sink includes a recess, an elastically resilient holding region and an opening for mounting at a common heat sink (10) of a lighting unit of a motor vehicle headlight and of a plastic optics of the LED-module in a form-fit and force-fit manner. The heat sink is formed with a tapered wall (5) by a bushing, which is closed by a base (6). An independent claim is also included for a method for mounting a LED-module.

Abstract (de)

Die vorliegende Erfindung betrifft ein insbesondere für Kraftfahrzeuge einsetzbares LED-Modul (1, 1b, 1c) zum Einbau in ein Leuchtaggregat, wobei das LED-Modul (1, 1b, 1c) mehrere LED-Bauelemente (3, 3b, 3c) umfasst, die auf einer Leiterplatte (2, 2b, 2c) derart montiert sind, dass sie unmittelbar oder mittelbar mit einem Kühlkörper (4, 4b, 4c) verbunden sind, wobei das LED-Modul (1, 1b, 1c) mindestens einen Kühlkörper (4, 4b, 4c) umfasst, der mit mindestens einem LED-Bauelement (3, 3b, 3c) verbunden ist, und der Montagemittel (8, 14, 15) für eine formschlüssige und/oder kraftschlüssige Montage an einem anderen Element (10, 16) des LED-Moduls (1, 1b, 1c) oder des Leuchtaggregats aufweist.

IPC 8 full level

**H01L 33/00** (2006.01); **F21V 29/00** (2006.01)

CPC (source: EP US)

**F21K 9/00** (2013.01 - EP US); **F21S 41/153** (2017.12 - EP US); **F21Y 2115/10** (2016.07 - EP US)

Citation (applicant)

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Citation (search report)

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- [X] WO 2006122392 A1 20061123 - TIR SYSTEMS LTD [CA], et al
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FR GB IT

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

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